

科技论文期末作业

题目: 论文精读与科技论文写作

姓	名:	秦宏志
学	号:	2201111518
院	系:	信息工程学院
专	<u>小</u> :	集成电路
研究	方向:	超临界流体
授课教授		朱跃生 教授

摘要

如课业目标所示, 学生在第一章为论文精读选择 Increasing Controllable Oxygen Ions to Improve Device Performance Using Supercritical Fluid Technique in ZnO-Based Resistive Random Access Memory 为来源进行阅读,其因有三,第一在于与自己的博士研究方向相关,其二这是由台湾团队所出得研究成果,最后该篇研究成果为引用了我的导师张冠张老师曾经发表过的文章。第二章为考核为找到 100 篇文章进行处理,最后用表格整理本作业所搜集的文献。

关键词: 科技论文写作

目录

论文精读	1
文精读资讯	1
文心得	1
前言	1
方法	1
结果	1
讨论	
摘要	
前言	2
参考又献搜集	13
	17
	23
	文精读资讯 文心得

主要符号对照表

x, y, m, n, t 标量, 通常为变量

K, L, D, M, N, T 标量,通常为超参数

 $x \in \mathbb{R}^D$ D 维列向量

 (x_1, \cdots, x_D) D 维行向量

 $(x_1, \dots, x_D)^T$ or $(x_1; \dots; x_D)^T$ D 维行向量

 $x \in \mathbb{R}^{KD}$ (KD) 维的向量

 M_i or $M_i(x)$ 第 i 列为 $\mathbf{1}($ 或者 x),其余为 $\mathbf{0}$ 的矩阵

diag(x) 对角矩阵,其对角元素为x

 I_N or I $(N \times N)$ 的单位阵

 $A \in \mathbb{R}^{D_1 \times D_2 \times \cdots \times D_K}$ 大小为 $D_1 \times D_2 \times \cdots \times D_K$ 的张量

 $\{x^{(n)}\}_{n=1}^{N}$ 集合 $\{(x^{(n)},y^{(n)})\}_{n=1}^{N}$ 数据集

 $N(x; \mu, \Sigma)$ 变量 x 服从均值为 μ ,方差为 Σ 的高斯分布

① 本符号对照表内容选自邱锡鹏老师的《神经网络与深度学习》[1]一书。

第一章 论文精读

从下面两处期刊来源,进行翻译、阅读并写出心得,而研究论文来源如下所示:

- 1. IEEE Transactions on Pattern Analysis and Machine Intelligence (TPAMI) (SCI IF 16.389), 2021.
- 2. IEEE Journal on Selected Areas in Communications (SCI IF 9.114), 2021.

而论文心得必须根据 IMRAD 的方式进行撰写,其流程分别为四部分,分别为前言 (Introduction)、方法 (Methods)、结果 (Results) 和讨论 (Discussion),最后则是根据原论文架构的范例。

1.1 论文精读资讯

下列论文资讯有二^[2], 其一为 arXiv 的 1810.08437 所示的资讯, 其二为 IEEE Transactions on Pattern Analysis and Machine Intelligence 的公开资讯。

Increasing Controllable Oxygen Ions to Improve Device Performance Using Supercritical Fluid Technique in ZnO-Based Resistive Random Access Memory 在 ZnO 基电阻随机存取存储器中使用超临界流体技术增加可控氧离子以提高器件性能

Sheng-Yao Chou, Chih-Cheng Yang, Ting-Chang Chang, Fellow, IEEE, Tsung-Ming Tsai, Shih-Kai Lin, Chan-Wei Kuo, Chung-Wei Wu, Yu-Bo Wang, and Simon M. Sze, Life Fellow, IEEE

1.2 论文心得

- , 该心得则根据 IMRAD 来分析。
- 1.2.1 前言
- 1.2.2 方法
- 1.2.3 结果
- 1.2.4 讨论

1.3 论文翻译

在此根据论文 Increasing Controllable Oxygen Ions to Improve Device Performance Using Supercritical Fluid Technique in ZnO-Based Resistive Random Access Memory 的章节

结构进行翻译,其论文题目的中文字面意义上为在 ZnO 基电阻随机存取存储器中使用超临界流体技术增加可控氧离子以提高器件性能。该根据原研究论文架构来分配章节。

1.3.1 摘要

在这项研究中,提出了一种先进的超临界流体 (SCF) 技术,适用于低温 (80 度 C) 和高压 (4000 psi) 的材料和电子设备,用于基于 ZnO 的电阻式随机存取存储器 (RRAM))。在 SCF 处理后,X 射线光电子能谱 (XPS) 分析证实氧化锌薄膜中氧离子的浓度增加。此外,电学测量证实,与未经处理的器件相比,经处理的 ZnO 基随机存取存储器具有较低的形成电压、较低的置位电压和较高的高低阻态比率。接下来,通过拟合电流-电压曲线来研究载流子传输机制。最后,引入物理模型来说明额外的氧离子,这些氧离子在 SCF 处理后在随机存取存储器中产生更好的记忆特性。这种重要的 SCF 技术在不改变原始元素比例的情况下增加了氧离子的含量,并保持了简单的器件结构。因此,该技术显示出可行的材料改进潜力,能够在不久的将来进行有效的实际应用。

1.3.2 前言

电阻式随机存取存储器(RRAM)将在不久的将来取代 FLASH 存储器成为主流的非易失性存储器 [1]-[7]。诸如简单的金属-绝缘体-金属结构、低功耗和高速等显着优势使 RRAM 最适合集成电路 [8]-[12]。过去,各种金属氧化物材料如 Ta2O5、HfO2 和 NiO 已被用作 RRAM 的中间层 [13]-[21]。除了这些材料之外,具有优异电阻开关 (RS) 特性的 ZnO 也已用于 RRAM 应用 [22]-[24]。

基于价态变化机制解释了基于氧化锌的 RRAM 中的 RS 机制。由开关层内的氧空位和间隙氧离子组成的导电丝 (CF) 的断裂和形成是通过在电极上施加不同的极性电势来确定的。氧离子通过电势迁移在 CF 附近引起氧化还原反应,从而引发 CF 电阻的变化。因此,控制 CF 附近的氧离子在 RRAM [25]-[28] 的性能中起着关键作用。在之前的研究中,开关层中不同浓度的氧离子可以提高器件性能 [29]、[30]。在一些研究中,氧储存层被诱导来改善器件性能。该层通常是氧化物绝缘体,具有高浓度的氧离子和空位,用于储存过量的氧气 [31]-[33]。在其他研究中,各种氧环境含量被诱导导致氧化物绝缘体中氧离子和空位浓度的增加 [34]-[36]。

此外,还应用了一种新型的超临界流体 (SCF) 处理来改进 RRAM 器件。SCF 具有高渗透性和高溶解性,很容易渗透到设备中。因此,一些研究使用插入水分子的超临界 CO2 流体来改善绝缘体性能 [30]、[37]、[38]。然而,在这项研究中,不需要在绝缘体中充气更多的氧气或插入另一种材料。该装置在制造过程中采用高压纯超临界 CO2 流体处理。无毒、化学特性稳定的高压超临界 CO2 流体可以渗透到纳米级结构中。凭借这些优异的特性,超临界 CO2 流体可以显着削弱 Zn-O 键,导致氧离子含量增加而不

改变原始元素比例。因此,超临界 CO2 流体技术是一种合适的物质,可应用于制造以改善氧化锌基 RRAM 的 RS 性能。在本研究中,由于其优异的物理性能,提出了超临界 CO2 流体处理。为了研究其对 ZnO 开关层增加过量氧离子和改善氧化锌基 RRAM 的影响,在处理前后进行了电测量和材料分析。此外,还进行了实验以证明物理模型在提高设备性能方面的有效性。

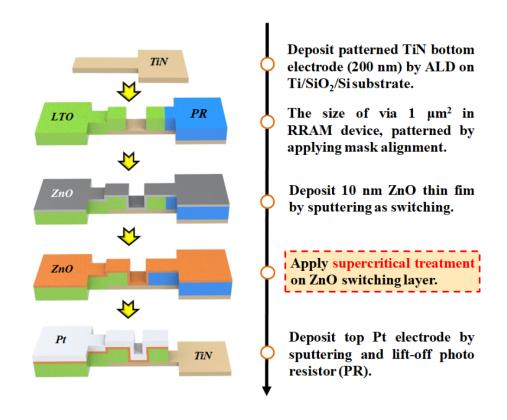


Fig. 1. Process flows for Pt/ZnO/TiN of RRAM device fabrication.

图 1.1 论文图 1

图 1. RRAM 器件制造的 Pt/ZnO/TiN of RRAM 工艺流程。

1.3.3 实验装置

两个实验样品的制造工艺流程如图 1 所示。首先,使用原子层沉积在两个图案化的 Ti/SiO2/Si 衬底上沉积 200 nm 氮化钛 (TiN) 作为底部电极。接下来,在这两个器件中,通孔的尺寸为 1 μm2,通过应用掩模对准进行图案化。10 nm ZnO 薄膜作为 RRAM器件的开关层,通过使用 30 sccm Ar 气体在 4 mTorr 的工作压力下溅射 ZnO 靶材而沉积。使用 N&K 1280 分析仪测量 ZnO 薄膜的厚度。随后,将其中一个样品引入 SCF 工艺。SCF 系统和处理步骤如图 2 所示。将样品置于反应室中,加热至 80 摄氏度。CO2

被注射泵压缩至 4000 psi 并引入反应室以达到临界点。CO2 进入 SCF 状态后,样品进行 1 h 处理。

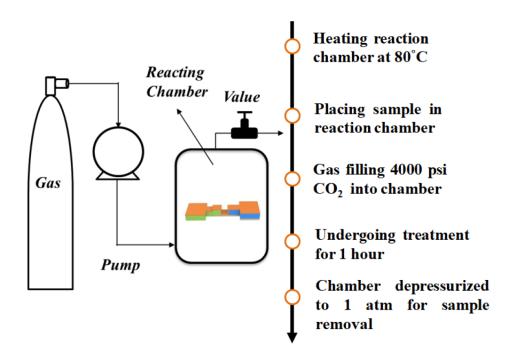


Fig. 2. SCF treatment system and treatment steps.

图 1.2 论文图 2

图 2 SCF 处理系统和处理步骤。

处理后,在取出样品之前将腔室减压至 1 个大气压。最后,随后通过直流溅射沉积作为两个样品的顶部电极的 200 nm 铂 (Pt)。为了识别 SCF 处理后 ZnO 薄膜的差异,制备了 Si 晶片上未经处理和处理的 10 nm ZnO 薄膜用于材料分析。为了识别 SCF 处理后 ZnO 薄膜的差异,制备了 Si 晶片上未经处理和处理的 10 nm ZnO 薄膜用于材料分析。X 射线光电子能谱(XPS)的材料分析是通过 JEOL JAMP-9500F 俄歇电子能谱仪获得的。使用 Agilent B1500A 半导体参数分析仪和 Cascade M150 微探针台在室温和环境大气中进行电流 - 电压 (I - V) 电气测量以观察处理和未处理 RRAM 的 RS 特性。直流电压提供给底部电极 (TiN),顶部电极 (Pt) 接地。

1.3.4 结果与讨论

为了证明 SCF 处理对器件的影响,对经过处理和未经处理的器件进行了 XPS 分析,如图 3 所示。如图 3(a)中的宽扫描 XPS 光谱所示,处理和未处理的 ZnO 薄膜的成分几乎相同 [39]-[42]。此外,对 ZnO 薄膜的 O 1 s 峰进行去卷积,以观察氧原子的不同状态。531.8 和 529.9 eV 处的去卷积峰分别与氧离子对键合缺陷的贡献和氧原子与 Zn

原子的键合有关 [43]-[46]。图 3 (b) 和 (c) 表明 SCF 处理后 Zn-O 键合的百分比显着降低。相比之下,氧离子的比例从 29% 增加到 77%。

基于 XPS 分析, SCF 处理通过增加用于切换的可控氧离子来改善 ZnO 层中的切换层。图 4显示了处理和未处理器件的开关特性。在切换器件之前,施加形成电压以激活切换特性。100μA 顺从电流下成形特性的双扫描 IV 曲线如图 4(a) 所示。蓝色和绿色箭头分别表示前向和后向扫描。后向扫描在成形过程后呈现导通状态电流。

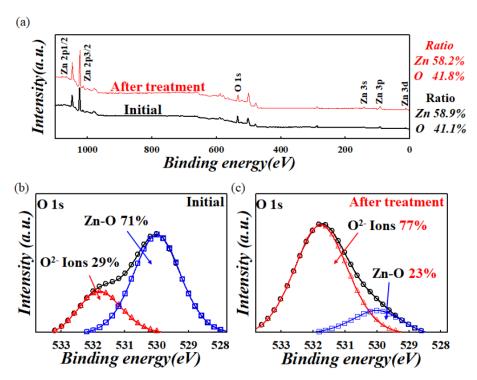


Fig. 3. XPS (a) wide-scan results for the ZnO film before (black line) and after (red line) SCF treatment. The right insets show the mole fraction ratio for each element. Narrow scan results for O 1 s (b) before treatment and (c) after treatment.

图 1.3 论文图 3

图 3.SCF 处理之前(黑线)和之后(红线)ZnO 薄膜的 XPS(a)宽扫描结果。右侧插图显示了每种元素的摩尔分数比。O 1 s (b)治疗前和 (c)治疗后的窄扫描结果。

图 4. (a) 处理和未处理器件成型过程的双扫描 IV 曲线。(b) 成型电压的统计分布。(c) 双极 I - V 曲线。(d) LRS 和 HRS 的统计分布: (e) VSET 和 (f) VRESET。

因此,当电流达到 100 μA 的顺从电流时,正向扫描中验证了 3.1 和 4.5 V 的形成电压。与未经处理的器件相比,经处理的器件的成型电压从 4.5 V 提高到 3.1 V。由于 SCF 处理增加了氧空位和氧离子,更多的导电路径导致形成电压降低。此外,收集十个随机点进行静态验证,以验证两种器件的形成电压的变化,如图 4 (b) 所示。

未经处理的器件的平均形成电压约为 4.5 V。相比之下, 处理后的器件表现出约 3.1

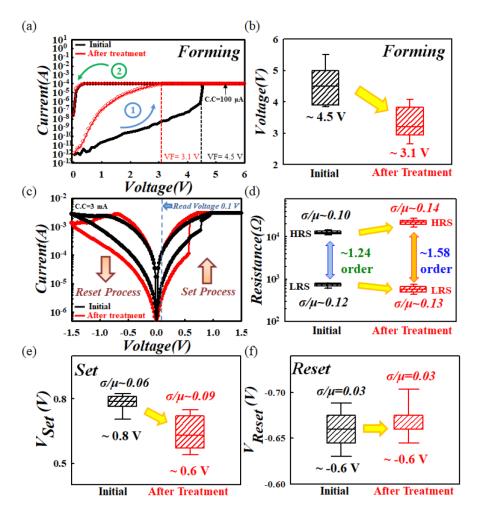


Fig. 4. (a) Double-sweep IV curves of the forming process in the treated and untreated devices. (b) Statistical distribution of the forming voltage. (c) Bipolar I - V curves. (d) Statistical distribution of LRS and HRS: (e) V_{SET} and (f) V_{RESET} .

图 1.4 论文图 4

V 的较低平均形成电压,表明 SCF 处理有效地改善了形成电压的降低。在形成过程之后,器件的电阻状态可以通过不同极性的电位来切换。

当底部电极受到正偏压时,器件会经历一个设置过程,并由于 CF 的形成而从高阻态 (HRS) 切换到低阻态 (LRS)。相反,当向底部电极施加负偏压时,器件会经历复位过程,并由于 CF 的破裂而从 LRS 切换到 HRS。处理和未处理器件的开关特性如图 4 (c) 所示。

I-V扫描在设置过程中以 1.5 V 偏置和 3 mA 顺从电流在器件上运行, 在复位过程中使用 -1.5 V 负偏置。增加氧离子和空位以改善 CF 曲线会导致更高的导通状态电流和更低的关断状态电流。

改善了设备处理后的设定电压和内存窗口,使设备功耗和设备 RS 的识别分别更

低和更容易。此外,收集了一个设备中的多个周期进行统计分析,以验证两个设备的 RS 特性和 VSET/VRESET 的变化,如图 4(d)-(f) 所示。

处理后的器械中 HRS 和 LRS 的比率为 1.6 个数量级,而未处理的器械中的比率为 1.2 个数量级,远低于处理过的器械。此外,提取两个设备的变化系数 (CV) 以验证变化。

两种设备中 LRS 和 HRS 的 CV 相似。VSET/VRESET 如图 4(e) 和 (f) 所示。经过处理的设备的 VSET 比未经处理的设备低 0.8 倍。经处理和未经处理的装置中 VSET 的 CV 分别为 0.06 和 0.09。两个器件中 VRESET 的 CV 均为 0.03。

处理过的设备中 VSET 的 CV 大于未处理过的设备。先前的一项研究还表明,由于氧离子的比例较高,在 ZnO 基开关层中观察到 VSET 的较大变化和较小的 VRESET 变化 [47]。在这项工作中,根据图 3 所示的 O 1 s XPS 结果,SCF 处理后氧离子的含量增加。切换层中更多的氧离子可用于设置过程。因此,建议的处理后设定电压降低。

然而,氧离子的增加也会导致设定过程中工作电压的较大变化。此外,HRS和LRS分布都证实了在所提出的处理后可以获得更高的内存窗口,这表明SCF技术是基于实验结果改进RRAM器件的有效方法。对于处理和未处理装置的均匀性,测量了五个未处理和五个具有相同结构的处理装置的多个HRS/LRS/VSET/VRESET循环的相应统计分布,如图5所示。

两种器件在 HRS/LRS/VSET/VRESET 方面均表现出良好的一致性。与未处理的设备相比,所有处理过的设备都具有更大的内存窗口,如图 5 (a) 和 (b) 所示。此外,所有处理过的设备都表现出比未经处理的设备更低的 VSET 值,如图 5 (c) 和 (d) 所示。两种器件中的 VRESET 相似,如图 5(e) 和 (f) 所示。

因此,SCF 技术是提高 RRAM 器件性能的有效方法。对于实际内存应用,两种器件的耐用性和保持性都被用来研究它们的可靠性,如图 6 所示。在图 6(a)和 (b)中,经处理和未经处理的装置在耐久试验中至少可操作 105 次。此外,在图 6 (c)和 (d)所示的保持测试中,它们的电阻状态能够保持至少 104 秒而没有任何退化。此外,处理过的设备表现出更大的内存窗口。两种器件中 HRS 的载流子传输机制均以肖特基机制为主。肖特基发射方程可以表示为

$$J = A^{**}T^{2} \exp \left[\frac{-q \left(\phi_{B} - \sqrt{qV/4\pi\varepsilon_{i}d_{\mathrm{sch}}} \right)}{k_{B}T} \right]$$

其中 A^{**} 、 ε_i 和 φ_B 分别是有效理查森常数、绝缘体介电常数和势垒高度 [48]。图中斜率和截距的物理意义可以通过计算肖特基方程的对数。

 $\ln \left(J/T^2 \right) - V^{0.5}$ 斜率和截距分别取决于势垒高度和肖特基距离,因为斜率和截距与

 $((1/\varepsilon_i d))^{1/2}$ 成正比和 φ_B ,其中 d 是肖特基距离。图 7(a) 和 (b) 表明两种器件的 HRS 均 受肖特基机制支配。

此外,处理后的器件具有较大的截距和斜率,对应于其较大的势垒高度和肖特基距离。基于当前拟合和材料分析的结果,提出了处理和未处理设备的模型,如图 8 所示。超临界 CO2 流体渗透到 ZnO 纳米结构中,由于 Zn-O 键合减弱而导致更多的氧离子。

经过 SCF 处理后,处理后的 ZnO 基 RRAM 可以在其氧化锌开关层中储存更多的氧离子,提高了运行过程中离子的可控性。因此,处理后的器件具有较好的 RS 特性,例如较低的形成电压、较小的 VSET 和较大的存储窗口。由于 CF 附近更多的氧离子参与氧化还原反应,因此肖克蒂距离和势垒高度比未处理的器件大,使得处理后的器件具有更大的 HRS 电阻和更好的记忆窗口。

图 5。LRS 和 HRS 在 (a) 五个未处理和 (b) 五个处理设备中的统计分布。VSET 在 (c) 五个未处理和 (d) 五个处理设备中的统计分布。VRESET 在 (e) 五个未处理 和 (f) 五个处理过的设备中的统计分布。

图 6. (a) 未处理设备和 (b) 处理设备保持测试的耐久性测试, (c) 未处理设备和 (d) 处理设备没有任何退化。

图 7. (a) 未处理的 RRAM 和 (b) 处理的 RRAM 的当前拟合结果。

图 8. 物理模型说明了 (a) 未处理的 RRAM 和 (b) 处理的 RRAM 的传导机制。

1.3.5 结论

经过 SCF 处理后,氧化锌基 RRAM 表现出更好的特性,包括更低的形成电压、更低的置位电压和更大的存储窗口。基于 XPS 分析,SCF 处理后开关层中的氧离子浓度增加,导致 RS 期间的氧化还原反应更加剧烈。SCF 技术可以被认为是一种有效的方法来增加各种氧化物基材料中氧离子的含量,这些材料被选为 RRAM 器件中的绝缘体。这种 SCF 技术加速了高性能 RRAM 器件的开发。

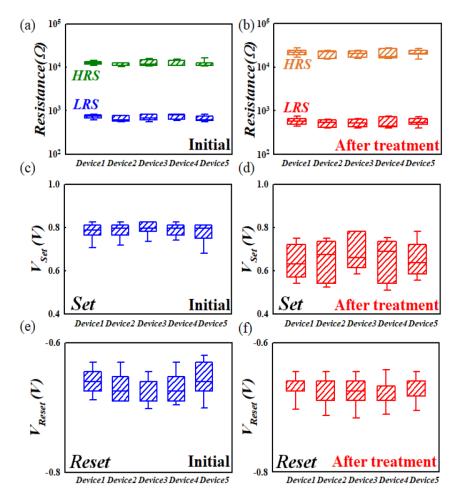


Fig. 5. Statistical distribution of the LRS and HRS in (a) five untreated and (b) five treated devices. Statistical distribution of V_{SET} in (c) five untreated and (d) five treated devices. Statistical distribution of V_{RESET} in (e) five untreated and (f) five treated devices.

图 1.5 论文图 5

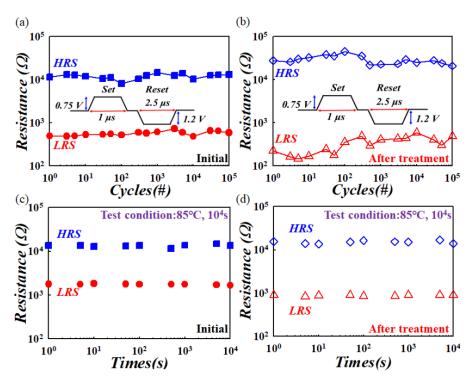


Fig. 6. Endurance tests in (a) untreated device and (b) treated device retention tests without any degradation in (c) untreated device and (d) treated device.

图 1.6 论文图 6

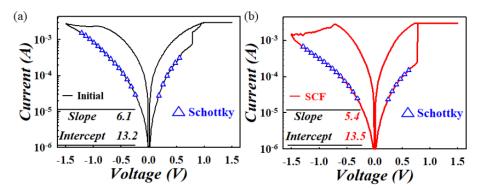


Fig. 7. Current fitting results for (a) untreated RRAM and (b) treated RRAM.

图 1.7 论文图 7

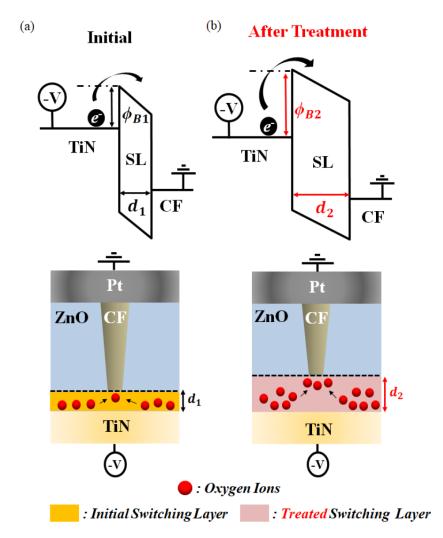


Fig. 8. Physical models illustrate the conducting mechanism for (a) untreated RRAM and (b) treated RRAM.

图 1.8 论文图 8

第二章 参考文献搜集

下列为本次作业所搜集而来的文献表,根据本次作业的 7 项来源进行搜集,其包括 IEEE Transaction/Magazine/Journal、IET (IEE) Proceeding/Magazine/Journal、ACM、Springer、Elsevier、Google 学术、Beidu 学术等,最后明确标示使用的平台搜寻引擎跟文献年份。

研究者	平台	来源分类	备注年份
Yingkun Xu et al.[3]	Baidu Scholar	IET (IEE) Proceeding	2019
Qin Wu et al. ^[4]	Baidu Scholar	IET (IEE) Proceeding	2020
Abimael Guzmán Pando et al. ^[5]	Baidu Scholar	IET (IEE) Proceeding	2020
Sarah Ahmed et al. ^[6]	Baidu Scholar	IET (IEE) Proceeding	2020
Francisco Luongo et al. ^[7]	Baidu Scholar	IET (IEE) Proceeding	2020

研究者	平台	来源分类	备注年份
Huiyun Gong et al.[8]	Google Scholar	IET (IEE) Proceeding	2021
Iman Iraei et al. ^[9]	Google Scholar	IET (IEE) Proceeding	2021
Yuling Xing et al.[10]	Google Scholar	IET (IEE) Proceeding	2021
Na Zhu et al.[11]	Google Scholar	IET (IEE) Proceeding	2021
Mohammad Ali Amirabadi et al.[12]	Google Scholar	IET (IEE) Proceeding	2021
Yanlin Wu et al. ^[13]	Google Scholar	IET (IEE) Proceeding	2021
Jiawei Nian et al.[14]	Google Scholar	IET (IEE) Proceeding	2021
Zhao Zhen et al.[15]	Google Scholar	IET (IEE) Proceeding	2021
Olarewaju Mubashiru Lawal et al.[16]	Google Scholar	IET (IEE) Proceeding	2021
Guanwen Zhang et al.[17]	Google Scholar	IET (IEE) Proceeding	2021
Azka Wani et al.[18]	Google Scholar	IET (IEE) Proceeding	2021
Hongxin Ji et al.[19]	Google Scholar	IET (IEE) Proceeding	2021
Junpeng Wu et al.[20]	Google Scholar	IET (IEE) Proceeding	2021
Chengxu Ma et al.[21]	Google Scholar	IET (IEE) Proceeding	2021
Mukesh Kumar Tripathi et al.[22]	Google Scholar	IET (IEE) Proceeding	2021

研究者	平台	来源分类	备注年份
Wei Liang et al. ^[23]	ACM	ACM Library	2021
Wu Q et al. [24]	ACM	ACM Library	2021
Chiyuan Zhang et al.[25]	ACM	ACM Library	2021
Kaixuan Chen et al. [26]	ACM	ACM Library	2021
Shervin Minaee et al. [27]	ACM	ACM Library	2021
Guansong Pang et al.[28]	ACM	ACM Library	2021
Garvit Goel et al. ^[29]	ACM	ACM Library	2021
Tom van der Weide et al. ^[30]	ACM	ACM Library	2021
Abdul Wasay et al.[31]	ACM	ACM Library	2021
Matthew Kusz et al.[32]	ACM	ACM Library	2021

研究者	平台	来源分类	备注年份
Hironobu Fujiyoshi et al. ^[33]	ScienceDirect	Elsevier	2021
Geert Litjens PhD et al.[34]	ScienceDirect Elsevier		2019
George Onoufriou et al.[35]	ScienceDirect	Elsevier	2019
A.Inés et al. ^[36]	ScienceDirect	Elsevier	2019
Jihoon Oh et al.[37]	ScienceDirect	Elsevier	2019

研究者	平台	来源分类	备注年份
Carole H. Sudre et al. ^[38]	Springer	Springer Link	2017
Mohammad Hesam Hesamian et al.[39]	Springer	Springer Link	2019
Pim Moeskops et al. ^[40]	Springer	Springer Link	2016
Niall O' Mahony et al.[41]	Springer	Springer Link	2019
Huazhu Fu et al.[42]	Springer	Springer Link	2016

研究者	平台	来源分类	备注年份
Sarah Adel Bargal et al.[43]	Google Scholar	IEEE Transactions	2021
Xu Yang et al.[44]	Google Scholar	IEEE Transactions	2021
Mingjie Sun et al.[45]	Google Scholar	IEEE Transactions	2021
Piotr Koniusz et al. ^[46]	Google Scholar	IEEE Transactions	2021
Jianfeng Dong et al.[47]	Google Scholar	IEEE Transactions	2021
Aysegul Dundar et al.[48]	Google Scholar	IEEE Transactions	2021
Yulin Wang et al.[49]	Google Scholar	IEEE Transactions	2021
Lucas Zimmer et al. ^[50]	Google Scholar	IEEE Transactions	2021
Maosen Li et al. ^[51]	Google Scholar	IEEE Transactions	2021
Yang Zhang et al. ^[52]	Google Scholar	IEEE Transactions	2021
Kaiyang Zhou et al. ^[53]	Google Scholar	IEEE Transactions	2021
Kai Zhao et al. ^[54]	Google Scholar	IEEE Transactions	2021
Piotr Koniusz et al. ^[55]	Google Scholar	IEEE Transactions	2021
Wenguan Wang et al. ^[56]	Google Scholar	IEEE Transactions	2021
Xiangbo Shu et al. ^[57]	Google Scholar	IEEE Transactions	2021
Wenguan Wang et al.[58]	Google Scholar	IEEE Transactions	2021
Jun Ma et al. ^[59]	Google Scholar	IEEE Transactions	2021
Jibin Wu et al. ^[60]	Google Scholar	IEEE Transactions	2021
Zhihua Wang et al.[61]	Google Scholar	IEEE Transactions	2021
Linjiang Huang et al. [62]	Google Scholar	IEEE Transactions	2021
Nicolas Gillis et al. ^[63]	Google Scholar	IEEE Transactions	2021
Zhi-Hao Lin et al. ^[64]	Google Scholar	IEEE Transactions	2021
Guohao Li et al. ^[65]	Google Scholar	IEEE Transactions	2021
Keren Fu et al. [66]	Google Scholar	IEEE Transactions	2021
Elvin Isufi et al. [67]	Google Scholar	IEEE Transactions	2021
Yawei Luo et al. ^[68]	Google Scholar	IEEE Transactions	2021
Jiangliu Wang et al. [69]	Google Scholar	IEEE Transactions	2021
Mehdi Ali et al. ^[70]	Google Scholar	IEEE Transactions	2021
Lin Wang et al. ^[71]	Google Scholar	IEEE Transactions	2021
Xiaosong Zhang et al. ^[72]	Google Scholar	IEEE Transactions	2021

研究者	平台	来源分类	备注年份
Filippo Maria Bianchi et al. [73]	IEEE Xplore	IEEE Transactions	2021
Xingang Pan et al. ^[74]	IEEE Xplore	IEEE Transactions	2021
Shervin Minaee et al. ^[75]	IEEE Xplore	IEEE Transactions	2021
Xuan Zhang et al. ^[76]	IEEE Xplore	IEEE Transactions	2021
Rui Zhang et al.[77]	IEEE Xplore	IEEE Transactions	2021
Hongyang Gao et al.[78]	IEEE Xplore	IEEE Transactions	2021
Kai Zhang et al. ^[79]	IEEE Xplore	IEEE Transactions	2021
Ke Yu et al. ^[80]	IEEE Xplore	IEEE Transactions	2021
Zilong Huang et al.[81]	IEEE Xplore	IEEE Transactions	2021
Ming-Kun Xie et al. [82]	IEEE Xplore	IEEE Transactions	2021
Chaoyou Fu et al.[83]	IEEE Xplore	IEEE Transactions	2021
Mang Ye et al. ^[84]	IEEE Xplore	IEEE Transactions	2021
Hongshuang Zhang et al.[85]	IEEE Xplore	IEEE Transactions	2021
Hanqing Chao et al. [86]	IEEE Xplore	IEEE Transactions	2021
Zerong Zheng et al. ^[87]	IEEE Xplore	IEEE Transactions	2021
Lei Cai et al. ^[88]	IEEE Xplore	IEEE Transactions	2021
Xuanyi Dong et al.[89]	IEEE Xplore	IEEE Transactions	2021
Xinyu Chen et al. [90]	IEEE Xplore	IEEE Transactions	2021
Mathew Monfort et al.[91]	IEEE Xplore	IEEE Transactions	2021
Deng-Ping Fan et al. [92]	IEEE Xplore	IEEE Transactions	2021
Joey Tianyi Zhou et al.[93]	IEEE Xplore	IEEE Transactions	2021
Zhentao Tan et al. ^[94]	IEEE Xplore	IEEE Transactions	2021
Zhichao Lu et al. ^[95]	IEEE Xplore	IEEE Transactions	2021
Yi Liu et al. ^[96]	IEEE Xplore	IEEE Transactions	2021
Jie Mei et al. ^[97]	IEEE Xplore	IEEE Transactions	2021
Adnan Siraj Rakin et al. [98]	IEEE Xplore	IEEE Transactions	2021
Jiayuan Li et al.[99]	IEEE Xplore	IEEE Transactions	2021
Gan Sun et al.[100]	IEEE Xplore	IEEE Transactions	2021
Jian Liang et al.[101]	IEEE Xplore	IEEE Transactions	2021
Deng-Bao Wang et al.[102]	IEEE Xplore	IEEE Transactions	2021

参考文献

- [1] 邱锡鹏. 神经网络与深度学习[M/OL]. 北京: 机械工业出版社, 2020. https://nndl.github.io/.
- [2] GARCIA N, MORERIO P, MURINO V. Learning with privileged information via adversarial discriminative modality distillation[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2019.
- [3] XU Y, ZHOU X, CHEN S, et al. Deep learning for multiple object tracking: a survey[J]. IET Computer Vision, 2019.
- [4] WU Q, YAN F, CHAI Z, et al. Crowd counting by dual-branch scale-aware network with ranking loss constraints[J]. IET Computer Vision, 2020.
- [5] PANDO A G, CHACON-MURGUIA M I, CHACON-DIAZ L B. Human-like evaluation method for object motion detection algorithms[J]. IET Computer Vision, 2020.
- [6] AHMED S, AZIM T. Diversified Fisher Kernel: Encoding Discrimination in Fisher Features to Compete Deep Neural Models for Visual Classification Task[J]. IET Computer Vision, 2020.
- [7] LUONGO F, HAKIM R, NGUYEN J H, et al. Deep learning-based computer vision to recognize and classify suturing gestures in robot-assisted surgery[J]. Surgery, 2020.
- [8] GONG H, WANG S, ZHAO X, et al. Few-shot learning with relation propagation and constraint[J]. IET Computer Vision, 2021.
- [9] IRAEI I, FAEZ K. A motion parameters estimating method based on deep learning for visual blurred object tracking[J]. IET Image Processing, 2021.
- [10] XING Y, ZHU J. Deep learning-based action recognition with 3D skeleton: A survey[J]. CAAI Transactions on Intelligence Technology, 2021.
- [11] ZHU N, ZHAO G, ZHANG X, et al. Falling motion detection algorithm based on deep learning[J]. IET Image Processing, 2021.
- [12] AMIRABADI M A, KAHAEI M H, NEZAMALHOSSENI S A. Low complexity deep learning algorithms for compensating atmospheric turbulence in the free space optical communication system [J]. IET Optoelectronics, 2021.
- [13] WU Y, WANG G, WANG Z, et al. PCAF-Net: A liver segmentation network based on deep learning [J]. IET Image Processing, 2021.
- [14] NIAN J, WANG P, GAO H, et al. A deep learning-based attack on text CAPTCHAs by using object detection techniques[J]. IET Information Security, 2021.
- [15] ZHEN Z, ZHANG X, MEI S, et al. Ultra-short-term irradiance forecasting model based on ground-based cloud image and deep learning algorithm[J]. IET Renewable Power Generation, 2021.
- [16] LAWAL O M, ZHAO H. YOLOFig detection model development using deep learning[J]. IET Image Processing, 2021.
- [17] ZHANG G, RAO Y, WANG C, et al. A deep learning method for video-based action recognition [J]. IET Image Processing, 2021.

- [18] WANI A, S R, KHALIQ R. SDN-based intrusion detection system for IoT using deep learning classifier (IDSIoT-SDL)[J]. CAAI Transactions on Intelligence Technology, 2021.
- [19] JI H, CUI X, REN W, et al. Visual inspection for transformer insulation defects by a patrol robot fish based on deep learning[J]. IET Science, Measurement & Technology, 2021.
- [20] WU J, TANG S, LI X. An insulator inspection method based on deep learning applicable to multiscale and occlusion conditions[J]. The Journal of Engineering, 2021.
- [21] MA C, LI D, ZENG S, et al. An efficient framework for deep learning-based light-defect image enhancement[J]. IET Image Processing, 2021.
- [22] TRIPATHI M K, MAKTEDAR D D. Optimized deep learning model for mango grading: Hybridizing lion plus firefly algorithm[J]. IET Image Processing, 2021.
- [23] LIANG W, XIE S, ZHANG D, et al. A Mutual Security Authentication Method for RFID-PUF Circuit Based on Deep Learning[J]. ACM Transactions on Internet Technology, 2021.
- [24] Q W, C B, Z Z, et al. Equity2Vec: End-to-end Deep Learning Framework for Cross-sectional Asset Pricing[J]. 2nd ACM International Conference on AI in Finance, 2021.
- [25] ZHANG C, BENGIO S, HARDT M, et al. Understanding deep learning (still) requires rethinking generalization[J]. Communications of the ACM, 2021.
- [26] CHEN K, ZHANG D, YAO L, et al. Deep Learning for Sensor-based Human Activity Recognition: Overview, Challenges, and Opportunities[J]. ACM Computing Surveys, 2021.
- [27] MINAEE S, KALCHBRENNER N, CAMBRIA E, et al. Deep Learning–based Text Classification: A Comprehensive Review[J]. ACM Computing Surveys, 2021.
- [28] PANG G, SHEN C, CAO L, et al. Deep Learning for Anomaly Detection: A Review[J]. ACM Computing Surveys, 2021.
- [29] GOEL G, GONDHALEKAR A, QI J, et al. ComputeCOVID19+: Accelerating COVID-19 Diagnosis and Monitoring via High-Performance Deep Learning on CT Images[J]. ICPP 2021: 50th International Conference on Parallel Processing, 2021.
- [30] Van der WEIDE T, PAPADOPOULOS D, SMIRNOV O, et al. Versioning for End-to-End Machine Learning Pipelines[J]. DEEM'17: Proceedings of the 1st Workshop on Data Management for End-to-End Machine Learning, 2017.
- [31] WASAY A, CHATTERJEE S, IDREOS S. Deep Learning: Systems and Responsibility[J]. SIG-MOD/PODS '21: Proceedings of the 2021 International Conference on Management of Data, 2021.
- [32] KUSZ M, PETERS J, HUBER L, et al. Building Detection with Deep Learning[J]. PEARC '21: Practice and Experience in Advanced Research Computing, 2021.
- [33] FUJIYOSHI H, HIRAKAWA T, YAMASHITA T. Deep learning-based image recognition for autonomous driving[J]. IATSS Research, 2021.
- [34] PHD G L, PHD F C, PHD J M, et al. State-of-the-Art Deep Learning in Cardiovascular Image Analysis[J]. JACC: Cardiovascular Imaging, 2019.
- [35] ONOUFRIOU G, BICKERTON R, PEARSON S, et al. Nemesyst: A hybrid parallelism deep learning-based framework applied for internet of things enabled food retailing refrigeration systems

- [J]. Computers in Industry, 2019.
- [36] A.Inés, C.Domínguez, J.Heras, et al. DeepClas4Bio: Connecting bioimaging tools with deep learning frameworks for image classification[J]. Computers in Biology and Medicine, 2019.
- [37] OH J, YUN K, MAOZ U, et al. Identifying depression in the National Health and Nutrition Examination Survey data using a deep learning algorithm[J]. Journal of Affective Disorders, 2019.
- [38] SUDRE C H, LI W, VERCAUTEREN T, et al. Generalised Dice Overlap as a Deep Learning Loss Function for Highly Unbalanced Segmentations[J]. International Workshop on Multimodal Learning for Clinical Decision Support, 2017.
- [39] HESAMIAN M H, JIA W, HE X, et al. Deep Learning Techniques for Medical Image Segmentation: Achievements and Challenges[J]. Journal of Digital Imaging, 2019.
- [40] MOESKOPS P, WOLTERINK J M, van der VELDEN B H M, et al. Deep Learning for Multi-task Medical Image Segmentation in Multiple Modalities[J]. Medical Image Computing and Computer-Assisted Intervention –MICCAI 2016, 2016.
- [41] O' MAHONY N, CAMPBELL S, CARVALHO A, et al. Deep Learning vs. Traditional Computer Vision[J]. Advances in Computer Vision, 2019.
- [42] FU H, XU Y, LIN S, et al. DeepVessel: Retinal Vessel Segmentation via Deep Learning and Conditional Random Field[J]. Medical Image Computing and Computer-Assisted Intervention –MICCAI 2016, 2016.
- [43] BARGAL S A, ZUNINO A, PETSIUK V, et al. Guided Zoom: Zooming into Network Evidence to Refine Fine-Grained Model Decisions[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [44] YANG X, ZHANG H, CAI J. Deconfounded Image Captioning: A Causal Retrospect[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [45] SUN M, XIAO J, LIM E G, et al. Discriminative Triad Matching and Reconstruction for Weakly Referring Expression Grounding[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [46] KONIUSZ P, ZHANG H. Power Normalizations in Fine-grained Image, Few-shot Image and Graph Classification[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [47] DONG J, LI X, XU C, et al. Dual Encoding for Video Retrieval by Text[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [48] DUNDAR A, SHIH K, GARG A, et al. Unsupervised Disentanglement of Pose, Appearance and Background from Images and Videos[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [49] WANG Y, HUANG G, SONG S, et al. Regularizing Deep Networks with Semantic Data Augmentation[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [50] ZIMMER L, LINDAUER M, HUTTER F. Auto-Pytorch: Multi-Fidelity MetaLearning for Efficient and Robust AutoDL[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [51] LI M, CHEN S, CHEN X, et al. Symbiotic Graph Neural Networks for 3D Skeleton-based Human Action Recognition and Motion Prediction[J]. IEEE Transactions on Pattern Analysis and Machine

- Intelligence, 2021.
- [52] ZHANG Y, TSANG I, LUO Y, et al. Recursive Copy and Paste GAN: Face Hallucination from Shaded Thumbnails[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [53] ZHOU K, YANG Y, CAVALLARO A, et al. Learning Generalisable Omni-Scale Representations for Person Re-Identification[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [54] ZHAO K, HAN Q, ZHANG C B, et al. Deep Hough Transform for Semantic Line Detection[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [55] KONIUSZ P, WANG L, CHERIAN A. Tensor Representations for Action Recognition[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [56] WANG W, LAI Q, FU H, et al. Salient Object Detection in the Deep Learning Era: An In-depth Survey[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [57] SHU X, ZHANG L, QI G J, et al. Spatiotemporal Co-attention Recurrent Neural Networks for Human-Skeleton Motion Prediction[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [58] WANG W, ZHOU T, QI S, et al. Hierarchical Human Semantic Parsing with Comprehensive Part-Relation Modeling[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [59] MA J, ZHANG Y, GU S, et al. AbdomenCT-1K: Is Abdominal Organ Segmentation A Solved Problem[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [60] WU J, XU C, HAN X, et al. Progressive Tandem Learning for Pattern Recognition with Deep Spiking Neural Networks[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [61] WANG Z, MA K. Active Fine-Tuning from gMAD Examples Improves Blind Image Quality Assessment[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [62] HUANG L, HUANG Y, OUYANG W, et al. Two-Branch Relational Prototypical Network for Weakly Supervised Temporal Action Localization[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [63] GILLIS N, HIEN L T K, LEPLAT V, et al. Distributionally Robust and Multi-Objective Nonnegative Matrix Factorization[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [64] LIN Z H, HUANG S Y, WANG Y C F. Learning of 3D Graph Convolution Networks for Point Cloud Analysis[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [65] LI G, MUELLER M, QIAN G, et al. DeepGCNs: Making GCNs Go as Deep as CNNs[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [66] FU K, FAN D P, JI G P, et al. Siamese Network for RGB-D Salient Object Detection and Beyond [J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [67] ISUFI E, GAMA F, RIBEIRO A. EdgeNets: Edge Varying Graph Neural Networks[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [68] LUO Y, LIU P, ZHENG L, et al. Category-Level Adversarial Adaptation for Semantic Segmentation

- using Purified Features[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [69] WANG J, JIAO J, BAO L, et al. Self-supervised Video Representation Learning by Uncovering Spatio-temporal Statistics[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [70] ALI M, BERRENDORF M, HOYT C T, et al. Bringing Light Into the Dark: A Large-scale Evaluation of Knowledge Graph Embedding Models under a Unified Framework[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [71] WANG L, YOON K J. Knowledge Distillation and Student-Teacher Learning for Visual Intelligence: A Review and New Outlooks[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [72] ZHANG X, WAN F, LIU C, et al. Learning to Match Anchors for Visual Object Detection[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [73] BIANCHI F M, GRATTAROLA D, LIVI L, et al. Graph Neural Networks with Convolutional ARMA Filters[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [74] PAN X, ZHAN X, BO DAI D L, et al. Exploiting Deep Generative Prior for Versatile Image Restoration and Manipulation[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [75] MINAEE S, BOYKOV Y Y, PORIKLI F, et al. Image Segmentation Using Deep Learning: A Survey [J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [76] ZHANG X, JIAO L, GRANMO O C, et al. On the Convergence of Tsetlin Machines for the IDENTITY- and NOT Operators[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [77] ZHANG R, LI X, ZHANG H, et al. Geodesic Multi-Class SVM with Stiefel Manifold Embedding [J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [78] GAO H, LIU Y, JI S. Topology-Aware Graph Pooling Networks[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [79] ZHANG K, LI Y, ZUO W, et al. Plug-and-Play Image Restoration with Deep Denoiser Prior[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [80] YU K, WANG X, DONG C, et al. Path-Restore: Learning Network Path Selection for Image Restoration[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [81] HUANG Z, WEI Y, WANG X, et al. AlignSeg: Feature-Aligned Segmentation Networks[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [82] XIE M K, HUANG S J. Partial Multi-Label Learning with Noisy Label Identification[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [83] FU C, WU X, HU Y, et al. DVG-Face: Dual Variational Generation for Heterogeneous Face Recognition[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [84] YE M, SHEN J, LIN G, et al. Deep Learning for Person Re-identification: A Survey and Outlook [J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [85] ZHANG H, ZENG Y, LU H, et al. Learning to Detect Salient Object with Multi-source Weak Su-

- pervision[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [86] CHAO H, WANG K, HE Y, et al. GaitSet: Cross-view Gait Recognition through Utilizing Gait as a Deep Set[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [87] ZHENG Z, YU T, LIU Y, et al. PaMIR: Parametric Model-Conditioned Implicit Representation for Image-based Human Reconstruction[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [88] CAI L, LI J, WANG J, et al. Line Graph Neural Networks for Link Prediction[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [89] DONG X, LIU L, MUSIAL K, et al. NATS-Bench: Benchmarking NAS Algorithms for Architecture Topology and Size[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [90] CHEN X, SUN L. Bayesian Temporal Factorization for Multidimensional Time Series Prediction [J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [91] MONFORT M, PAN B, RAMAKRISHNAN K, et al. Multi-Moments in Time: Learning and Interpreting Models for Multi-Action Video Understanding[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [92] FAN D P, LI T, LIN Z, et al. Re-thinking Co-Salient Object Detection[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [93] ZHOU J T, ZHANG L, JIAWEI D, et al. Locality-Aware Crowd Counting[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [94] TAN Z, CHEN D, CHU Q, et al. Efficient Semantic Image Synthesis via Class-Adaptive Normalization[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [95] LU Z, SREEKUMAR G, GOODMAN E, et al. Neural Architecture Transfer[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [96] LIU Y, ZHANG D, ZHANG Q, et al. Part-Object Relational Visual Saliency[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [97] MEI J, CHENG M M, XU G, et al. SANet: A Slice-Aware Network for Pulmonary Nodule Detection [J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [98] RAKIN A S, HE Z, LI J, et al. T-BFA: Targeted Bit-Flip Adversarial Weight Attack[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [99] LI J. A Practical O(N2) Outlier Removal Method for Point Cloud Registration[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [100] SUN G, CONG Y, DONG J, et al. What and How: Generalized Lifelong Spectral Clustering via Dual Memory[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [101] LIANG J, HU D, WANG Y, et al. Source Data-absent Unsupervised Domain Adaptation through Hypothesis Transfer and Labeling Transfer[J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.
- [102] WANG DB, ZHANG ML, LIL. Adaptive Graph Guided Disambiguation for Partial Label Learning [J]. IEEE Transactions on Pattern Analysis and Machine Intelligence, 2021.

致谢

非常感谢科技论文写作课的朱跃生教授,在科技论文写作课让学生上充分了解科技论文写作的知识与观念,同时又透过 Overleaf 平台实作了 LaTeX 的各类模板与写法,该流程也改善了自己目前的开发与研究工作模式,最后感谢在这一学期来一起读书得同学们跟室友对我这个资深同学的帮助。